

## **WSP05N15**

N-Ch MOSFET

#### **General Description**

**Features** 

The WSP05N15 is the highest performance trench N-Ch MOSFET with extreme high cell density,which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF05N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

• Advanced high cell density Trench technology

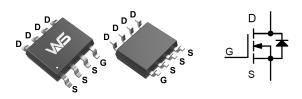
#### **Product Summery**

BVDSS	RDSON	ID
150V	37mΩ	6A

#### Applications

- Power Management for Boost Converters.
- Synchronous Rectifiers for SMPS.
- LED Backlighting.

#### **SOP-8 Pin Configuration**



#### Symbol Parameter Rating Units Drain-Source Voltage 150 $V_{DS}$ V Gate-Source Voltage v $\pm 25$ $V_{GS}$ Continuous Drain Current, V<sub>GS</sub> @ 10V<sup>1</sup> 6.0 А I<sub>D</sub>@T<sub>c</sub>=25℃ Continuous Drain Current, V<sub>GS</sub> @ 10V<sup>1</sup> 4.8 А I<sub>D</sub>@T<sub>c</sub>=70℃ Pulsed Drain Current<sup>2</sup> 24 А $I_{DM}$ Single Pulse Avalanche Energy<sup>3</sup> EAS 36 mJ Avalanche Current А $I_{AS}$ 12 W P<sub>D</sub>@T<sub>A</sub>=25℃ Total Power Dissipation<sup>4</sup> 3.5 Storage Temperature Range T<sub>STG</sub> -55 to 150 °C °C ΤJ **Operating Junction Temperature Range** -55 to 150

### Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		70	°C/W	
R <sub>eJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		24	°C <b>/W</b>	

### **Absolute Maximum Ratings**

Super Low Gate Charge

Green Device Available

Excellent Cdv/dt effect decline



**N-Ch MOSFET** 

#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	150			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!{\rm C}$ , I_D=1mA		0.098		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =6A		37	45	-mΩ
		V <sub>GS</sub> =6V , I <sub>D</sub> =2A		48	78	
V <sub>GS(th)</sub>	Gate Threshold Voltage	—V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.0	3.0	4.0	V
_V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient			-5.52		mV/℃
	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =25 $^{\circ}$ C			10	
I <sub>DSS</sub>		V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			100	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =3A		6.2		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.5	3.2	Ω
Qg	Total Gate Charge (10V)	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =3A		23	33	nC
Q <sub>gs</sub>	Gate-Source Charge			6		
Q <sub>gd</sub>	Gate-Drain Charge			9.9		
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =6Ω I <sub>D</sub> =1A ,R∟=30Ω.		5.5	21.6	
Tr	Rise Time			27	48.6	- ns
T <sub>d(off)</sub>	Turn-Off Delay Time			56	112	
T <sub>f</sub>	Fall Time			24	48	
Ciss	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz		1160	1500	
C <sub>oss</sub>	Output Capacitance			90		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			45		]

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.5mH , I <sub>AS</sub> =12A	30			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	$V_G = V_D = 0V$ , Force Current			4.0	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				24	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =4A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	IF=6A, dI/dt=100A/µs,Tյ=25℃		31		nS
Q <sub>rr</sub>	Reverse Recovery Charge			50		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, \text{L=}0.5\text{mH}, \text{I}_{\text{AS}}\text{=}12\text{A}$ 

4.The power dissipation is limited by 150  $^\circ\!\mathrm{C}$   $\,$  junction temperature

5.The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



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#### **N-Ch MOSFET**

#### **Typical Characteristics**

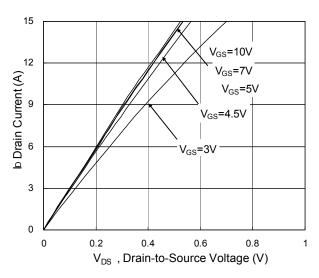


Fig.1 Typical Output Characteristics

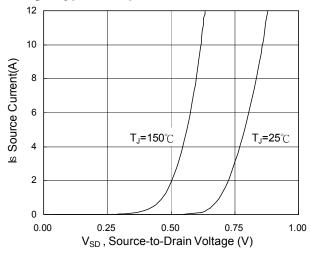


Fig.3 Forward Characteristics Of Reverse

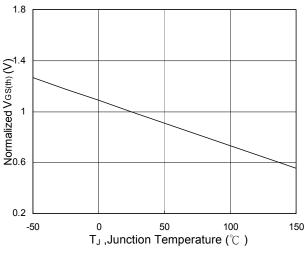


Fig.5 Normalized  $V_{GS(th)}$  vs. T<sub>J</sub>

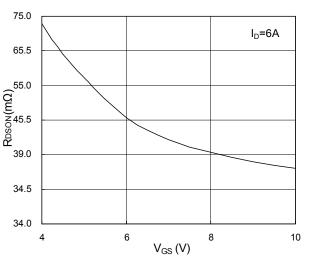


Fig.2 On-Resistance vs. Gate-Source

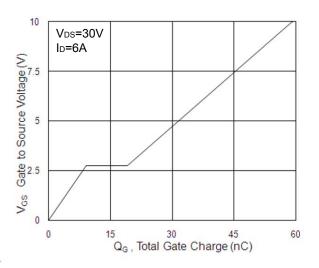


Fig.4 Gate-Charge Characteristics

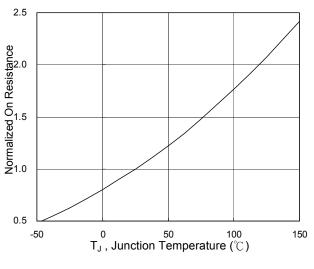


Fig.6 Normalized  $R_{\text{DSON}}$  vs.  $T_{\text{J}}$ 

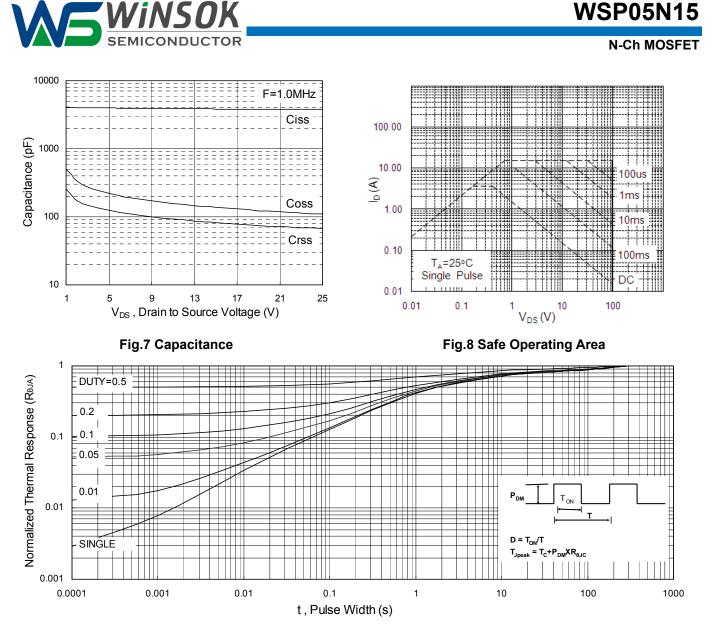
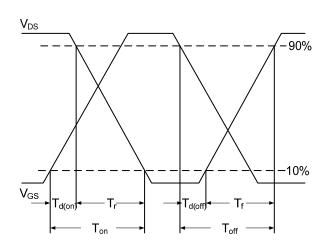
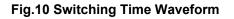


Fig.9 Normalized Maximum Transient Thermal Impedance





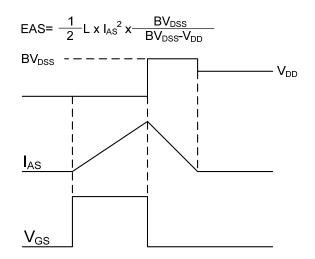


Fig.11 Unclamped Inductive Switching Waveform



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